

Magnetic-SMT-Buzzer without oscillator and with washing label

Electrical and Acoustical Parameter

Rated Voltage (V)	6.0
Operating Voltage (V)	4.0-7.0
Current Consumption* (mA)	Max. 50
Coil Resistance (Ω, ±5)	45
Sound Pressure Level* (dBA @ 10cm)	Min. 90
Resonance Frequency (Hz ±300)	2400

Remark: * Applying rated voltage (Resonant frequency, 1/2duty, Square wave)

Mechanical, Environmental Parameter

Contact / Wire	Pin
Operating Temperature (°C)	-40~+70
Storage Temperature (°C)	-40~+80
Housing Material	PPO
Housing Colour	Black
Component Weight (g)	2.0
Remark:	n.a.

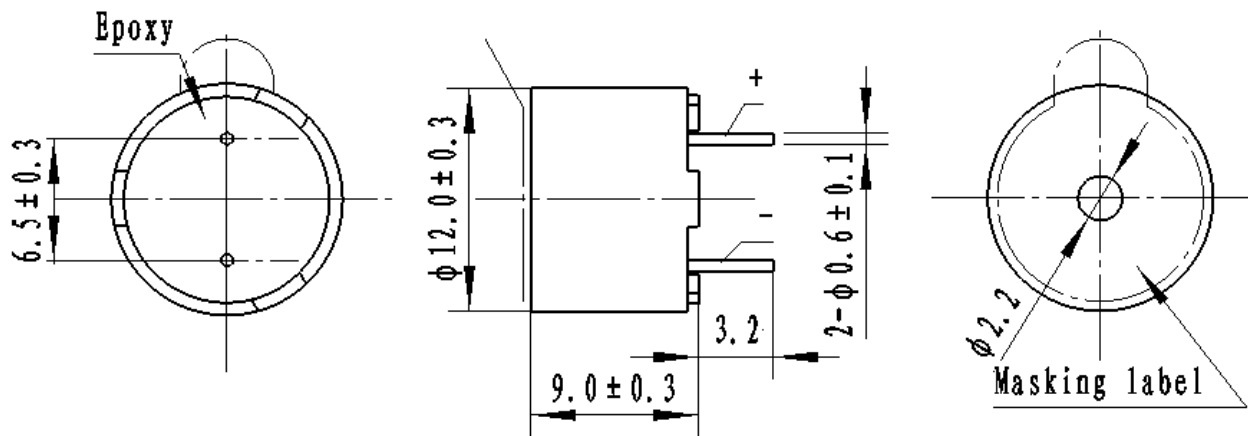
Approval

RoHs	<input checked="" type="checkbox"/>
REACH	<input checked="" type="checkbox"/>

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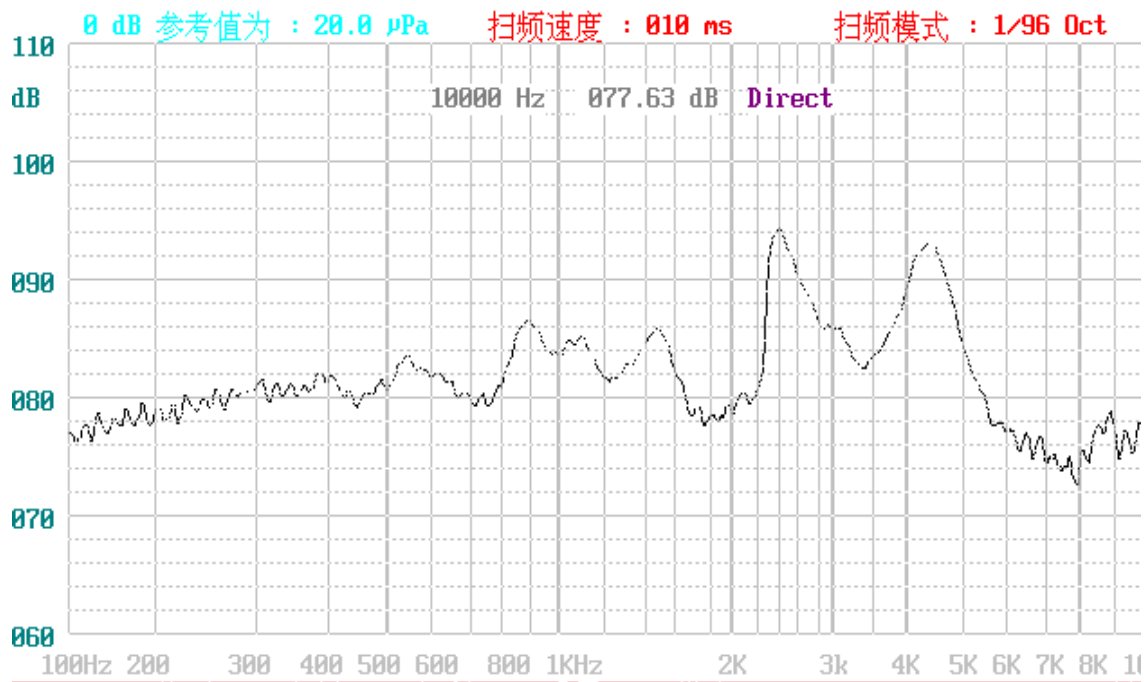
Drawing of Component and PCB Footprint

Unit: mm



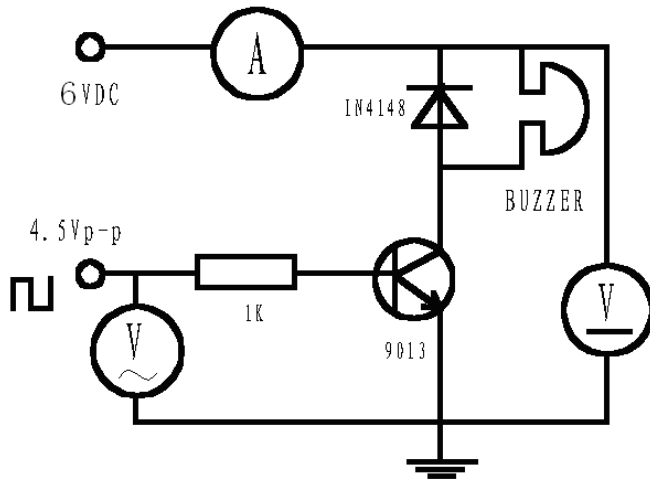
Dimensions without tolerance ± 5 mm

Frequency Response

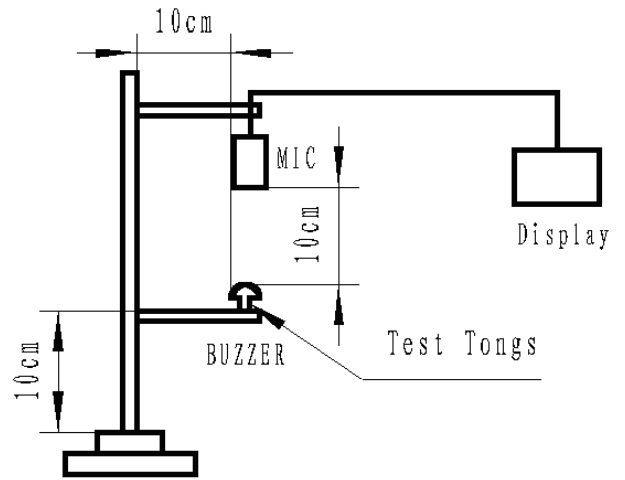


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Test Method



Test Circuit

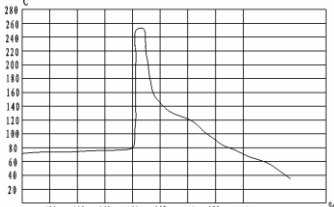


Test Equipis

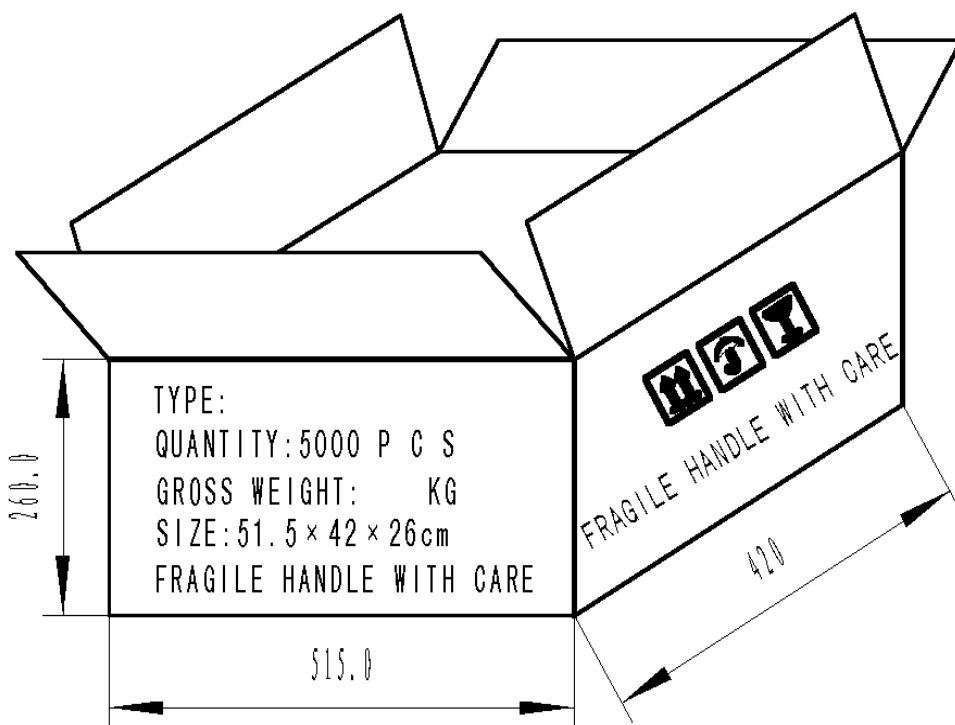
Reliability Test

NO.	ITEM	TESTING CONDITION	VARIANCE AFTER TEST
1	Humidity	50±5°C, 93(+2/-3)%RH, 96HRS	All specifications must be satisfied after the test.
2	High temp.	+80±2°C, 96HRS	
3	Low temp.	-30±2°C, 96HRS	
4	Temperature Cycling	-30±2°C, 30minutes room temp. 15 minutes +80±2°C, 30 minutes room temp. 15 minutes 5 cycles	
5	Drop test	3 times from height of 70cm onto the surface of 10mm thick wooden board.	
6	Vibration test	Make the test for the directions of X Y and Z (total 0.5 hours). To-and-fro. sweep time (from 10 to 55 Hz and then from 55 to 10 Hz) under single amplitude of 1.0mm is 1 minute.	

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7	Solder heat resistance	The part leads (pins) shall be immersed in molten solder maintained at $250 \pm 10^\circ\text{C}$ for a period of 30 seconds.	After the test part shall meet specifications without any degradation in appearance and performance.
8	Wave Soldering		

Packaging Information



NOTES:

1. 1.100 PCS per box
2. Total 50 boxes per carton
3. Total 5000 PCS carton
4. Volume: $51.5 \times 42 \times 26\text{cm}$

Revision Table

Index Nr.	Reason - Procedure Change description	Date	Name	Comments

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